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J.Wmo

TESSERA 3.3-018 CONT CONT 2-DIV.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of
Khandros et al.

Group Art Unit:

Divisional Application of
Prior Application Serial No. 08/861,280

Examiner:

Filed: Herewith

Date: December 3, 1997

For: **SEMICONDUCTOR CHIP ASSEMBLIES,
METHODS OF MAKING SAME AND
COMPONENTS FOR SAME**

X

Assistant Commissioner For Patents
Box Patent Application
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

After according a filing date to the above-identified Rule 53(b)

Divisional Application, please amend the application as follows:

In the Claims:

Cancel claims 1-60.

Insert new claims 61-70 as follows:

B1
AT
61. A semiconductor chip assembly comprising:

(a) a semiconductor chip having a front surface defining the top of the chip, said front surface including a central region and a peripheral region surrounding said central region, whereby said central region is disposed inwardly of said peripheral region, said chip having central contacts disposed in said central region

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